

Amendments to the Claims

Please cancel claims 1, 2, 7-15 and 18 amend claim 4 as follows. This listing of the claims will replace all prior versions, and listings, of the claims in this application.

1-3 (canceled).

4. (currently amended) A device (12) to pick up at least one disc-shaped semi-conductor wafer (11) from a container (14) of such wafers on one side (15) of an aperture (13) in the transfer station (10) of a semi-conductor wafer processing plant, the device being situated in the space (16) on the opposite side (17) of the said aperture, the device incorporating a moving shutter (1) designed to move between a first, closed aperture, position and a second, open aperture, position allowing access to the interior of the container, a means of moving (18) this shutter between these first and second positions, the said movement taking place, at least in part, in a plane approximately parallel to the plane of the aperture, the said device is ***identifiable in that*** it incorporates:

means of picking up (2) at least one semi-conductor wafer (11) by partially entering the container below a wafer and then picking up the wafer by its rim,

means of moving (3) the said pick-ups (2) between the space on the second side of the aperture and the first side, and back again,

means of linking (4) the said shutter with the said pick-up mechanism,

the said pick-ups (2) incorporate [[a]] first (6) and second (7) moving arms designed to adopt an initial position in which they lie approximately parallel and a second position in which they form a specific angle (α) to one another such that they form a flat, support structure for the semi-conductor wafer (11).

5. (original) A device according to Claim 4, ***identifiable in that*** the said wafer pick-ups (2) incorporate at least three rollers (21) attached to three extremities of the said first (6) and second (7) arms by means of a freely-rotating attachment such that the said three or more rollers are divided around the semi-conductor wafer (11) when the first and second arms are in their said second moving arm position.

6. (previously presented) A device according to Claim 4, ***identifiable in that*** the said first (6) and second (7) moving arms lie in a region vertically above the moving shutter (1) when in

their initial moving arm position and in a region laterally offset from the plane of the aperture when they are in their second moving arm position.

7-15 (cancelled)

16. (previously presented) A device according to Claim 4, *identifiable in that* it incorporates some means of arresting (35) the pick-ups' (2) mechanism (3) and the said pick-ups in the initial moving arm position.

17. (previously presented) A device according to Claim 16, *identifiable in that* the said arresting means (35) for the pick-ups' (2) mechanism (3) and the pick-ups is coupled with the mechanism (31) of the drive roller (30) used to rotate the rim (19) of the semi-conductor wafer(s) such that the movement of the drive roller causes the movement of the arresting system.

18 (cancelled)

19. (previously presented) A device according to Claim 5, *identifiable in that* each of the said at least three rollers (21) has a lower portion, on which rests the wafer's lower rim surface, and an upper portion, engaging the wafer's rim.

20. (previously presented) A device according to Claim 5, *identifiable in that* each of the said at least three rollers (21) has a tapered base, on which rests the wafer's lower rim surface, and an upper cylindrical section, acting as a rotary stop mechanism for the wafer inside the rollers (21).

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